

## **AMENDMENTS TO THE CLAIMS**

Please amend the claims as follows:

1. (Currently Amended) A component of a film-forming device in which a thin film is formed on a substrate in the device using a film-forming material, the component of the film-forming device comprising:

a body having a back face and a top face and a large number of through holes each extending from the back face to the top face formed therein,

wherein one of the back face and the top face includes a surface on which the thin film ~~is adhered~~ adheres during use, and the through holes provide access from the other one of the back face and the top face to the thin film adhered on the surface, whereby a cleaning solution ~~is permitted to penetrate~~ penetrates into a boundary between the surface and the thin film adhered thereon during cleaning thereof; and

wherein the through holes have a diameter smaller than a size of any particle of the film-forming material or a plasma thereof, thereby preventing penetration of any particle of the film-forming material or the plasma thereof into the through hole.

2. (Cancel)

3. (Currently Amended) The component of a film-forming device according to claim 1 ~~or 2~~, wherein the through holes are formed in such a manner that they are not perpendicular to the surface of the body of the component.

4. (Currently Amended) The component of a film-forming device according to claim 1, further comprising a layer consisting of a metal film ~~that is~~ easily soluble in the cleaning solution, the metal film being provided on the surface thereof of the component prior to adherence of the thin film thereon during use.

5 – 14. (Cancelled)